



环境对应

CONFORMING TO ENVIRONMENTAL

◆对应RoHS管理物质 / Conforming to RoHS Directive

品种 TYPE	铝电解电容器 Aluminum Electrolytic Capacitors				塑胶薄膜电容器 Film Capacitors	
	贴片型 SMD	引线型 Lead Wire	基板自立型 Snap-in	螺栓端子型 Screw terminal	金属熔射型 Metallized	箔电极型 Foil
对应RoHS指令 RoHS Compliance	对应完毕/Complied					
铅 Lead	不含 / Not contain					
端子材质 Terminal material	(~φ10) Fe/Cu/Sn-0.5Bi (φ12.5~) Fe/Cu/Sn	Fe/Cu/Sn		铝 Aluminum	Fe/Cu/Sn or Cu/Sn	Fe/Cu/Sn
焊接耐热性 Resistance to Soldering heat	请参照「回流 焊允许条件」 Please find "Reflow Soldering Condition"	260℃波峰焊 260℃ Flow Soldering		焊接对象外 Not applicable	请参照「焊接作业」 Please find "Soldering Operation"	
镉 Cadmium	不含 / Not contain					
水银 Mercury	不含 / Not contain					
六价铬 Chrome(VI)	不含 / Not contain (*1)					
PBB PBDE	不含 / Not contain					
DEHP, BBP DBP, DIBP	不含 / Not contain					
RoHS对应品的标示 Identification for RoHS Compliance Parts	内外包装的标签上标示有RoHS Compliance Add "RoHS Compliance" marking on inner and outer carton label					

品种 TYPE	导电性高分子铝固体电解电容器 Conductive Polymer Aluminum solid electrolytic Capacitors		薄膜高分子积层电容器 Polymer Multi-Layer Capacitors		双电层电容器 Electric Double Layer Capacitors	
	PZ-CAP		贴片型 SMD	引线型 Lead Wire	引线型 Lead Wire	
对应RoHS指令 RoHS Compliance	对应完毕/Complied					
铅 Lead	不含 / Not contain					
端子材质 Terminal material	引线型 Lead	Fe/Cu/Sn	Brass/Cu/Sn or Brass/Cu paste/Sn	Fe/Cu/Sn	Fe/Cu/Sn	
焊接耐热性 Resistance to Soldering heat	贴片型 SMD	Fe/Cu/Sn-0.5Bi	260℃回流焊/波峰焊 260℃ Reflow/Flow (*3)	260℃波峰焊 260℃ Flow Soldering	260℃波峰焊 260℃ Flow Soldering	
	引线型 Lead	260℃波峰焊 260℃ Flow Soldering				
镉 Cadmium	不含 / Not contain					
水银 Mercury	不含 / Not contain					
六价铬 Chrome(VI)	不含 / Not contain (*1)					
PBB PBDE	不含 / Not contain					
DEHP, BBP DBP, DIBP	不含 / Not contain					
RoHS对应品的标示 Identification for RoHS Compliance Parts	内外包装的标签上标示有RoHS Compliance Add "RoHS Compliance" marking on inner and outer carton label					

*1:螺栓端子型的固定带:三价铬镀层/Band of Screw terminal type:Chromium(III)

*2:详细内容请参照「回流焊接允许条件」./Please find "Reflow Soldering Condition".

*3:MPLCAP@ST系列只能进行回流焊接。/ST series shall be used in only reflow method.

◆关于遵守欧洲 REACH 规定 / Regarding compliance to European REACH Regulation

根据2008年5月26日发布的RIP3.8TGD (Technical Guidance Document)的内容, 本公司制造的电子部件为“无意图发放的成品”, 因此不适用欧洲REACH规定的第7条第1项的“注册”条款。

According to the content of RIP3.8TGD(Technical Guidance Document) which is published on 26 May 2008, our electronic components are "articles without any intended release." Therefore the are not applicable for "Registration"for European REACH Regulation Article 7(1).